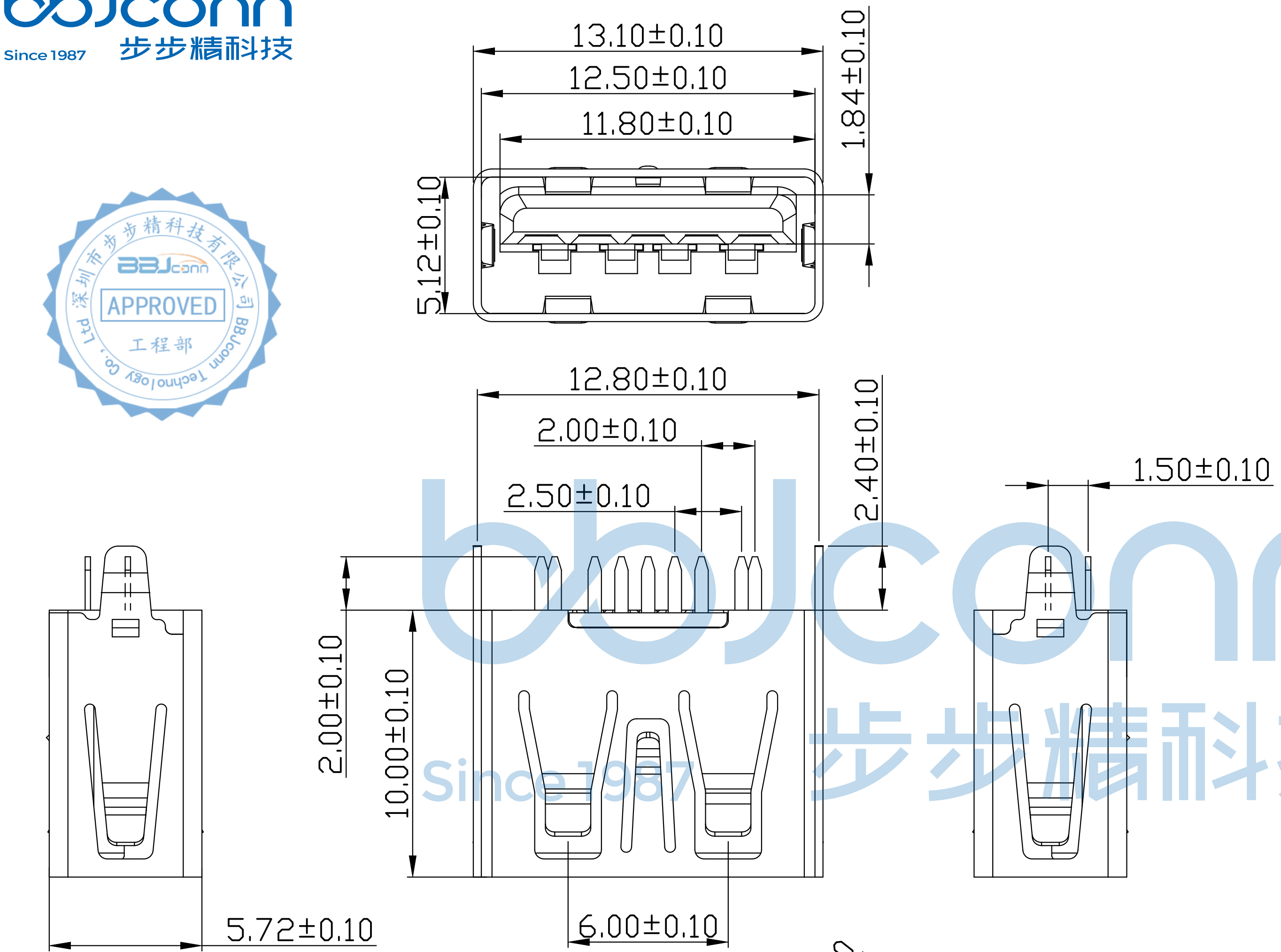
bbJconn
Since 1987 步步精科技

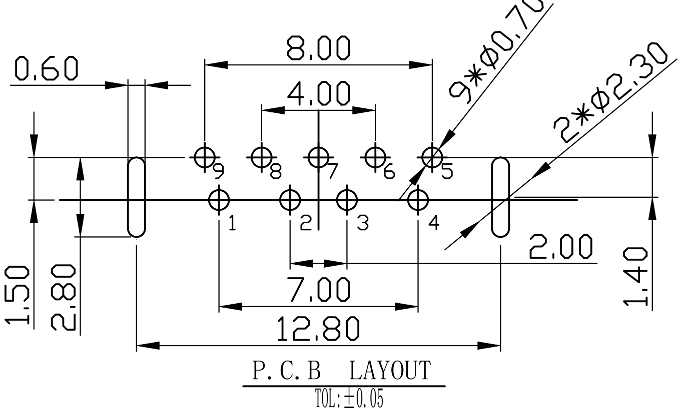
REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTE:
1.MATERIAL:
  1.1 INSULATOR:PBT & PA9T &LCP
  1.2 CONTACT:COPPER ALLOY C5191
  1.3 SHELL:SUS201 SPCC
2.ELECTRICAL CHARACTERISTICS;
  2.1 CONTACTRESISTANCE:30mΩ MAXIMUM
  2.2 CONTACT CURRENT RATING:1.5A
  2.3 DIELECTRIC WITHSTANDING VOLTAGE:100 V R.M.S.
  2.4 INSULATION RESISTANCE 100 MEGOHMS MIN
  2.5 OPERATING TEMPEROTURE:-20° C ～ 60° C
3.PLATING
  3.1 TERMINAL:
    50u″ MIN NICKEL ALL OVER
    100u″MIN Tin ON SOLDER AREA
    (1~30)u″Au ON CONTACT AREA
  3.2 SHELL:80u″MIN.NICEL ALL OVER

深圳市步步精科技有限公司
BBJconn
APPROVED
工程部
BBJconn Technology Co., Ltd

BBJconn Technology Co., Ltd
RoHS
Green Product Compliant





P.C.B LAYOUT
TOL:±0.05

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

PDWG,NO: 0471-1

深圳市步步精科技有限公司

.X: ±0.38 X°: ±3°
.XX: ±0.25 .X°: ±2°
.XXX: ±0.13 .XX°: ±1°

NAME: USB 3.0 AF 180度 H=10.0 直脚 直插 端子DIP 平口 LCP蓝胶 铁壳

APPD.: JM_Zheng
CHKD.: LYX
DR.: TSP

PJ. NO.: 127-275-090002-Y4G
SIZE: A4
DRW NO.:
FINISH: SEE NOTES
MAT'L.: SEE NOTES
SCALE: N/A
REV.: A0
UNIT: mm
PAGE: 1/2

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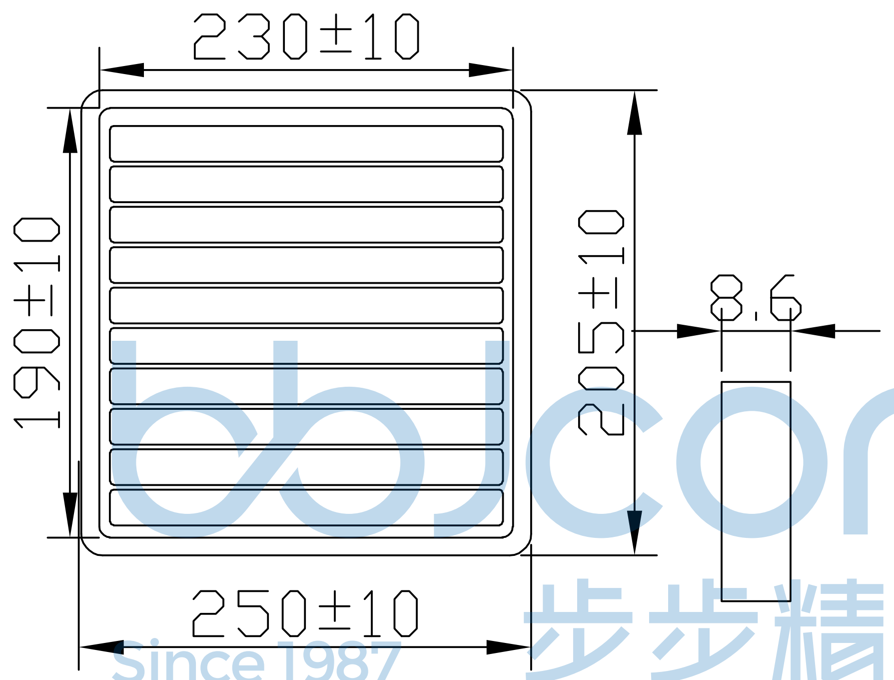

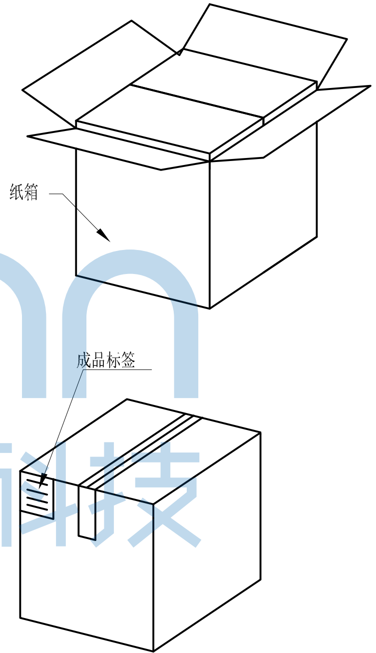

纸箱规格：350*210*290

1. 包装要求:

1.1 每盒吸塑盒包装100pcs;

1.2 每20盘放一箱,共计2000PCS;

1.3 纸箱外贴上标签。

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